

74LVTH125

Low Voltage Quad Buffer with 3-STATE Outputs

Features

- Input and output interface capability to systems at 5V V_{CC}
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink $-32\text{mA}/+64\text{mA}$
- Functionally compatible with the 74 series 125
- Latch-up performance exceeds 500mA
- ESD performance:
 - Human-body model > 2000V
 - Machine model > 200V
 - Charged-device model > 1000V

General Description


The LVTH125 contains four independent non-inverting buffers with 3-STATE outputs.

These buffers are designed for low-voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVTH125 is fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining a low power dissipation.

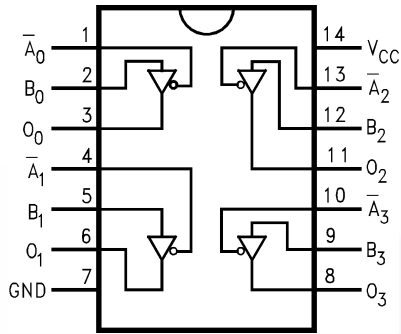
Ordering Information

| Order Number | Package Number | Package Description |
|--------------|----------------|--|
| 74LVTH125M | M14A | 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| 74LVTH125SJ | M14D | 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LVTH125MTC | MTC14 | 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

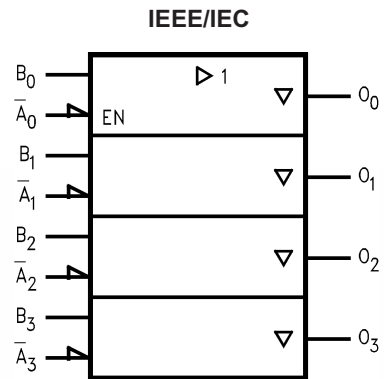
Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

 All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram



Logic Symbol



Pin Description

| Pin Names | Description |
|------------------|-----------------|
| \bar{A}_n, B_n | Inputs |
| O_n | 3-STATE Outputs |

Truth Table

| Inputs | | Output |
|-------------|-------|--------|
| \bar{A}_n | B_n | O_n |
| L | L | L |
| L | H | H |
| H | X | Z |

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = HIGH Impedance

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating |
|-----------|---|-----------------|
| V_{CC} | Supply Voltage | -0.5V to +4.6V |
| V_I | DC Input Voltage | -0.5V to +7.0V |
| V_O | DC Output Voltage Output in 3-STATE | -0.5V to +7.0V |
| | Output in HIGH or LOW State ⁽¹⁾ | -0.5V to +7.0V |
| I_{IK} | DC Input Diode Current, $V_I < GND$ | -50mA |
| I_{OK} | DC Output Diode Current, $V_O < GND$ | -50mA |
| I_O | DC Output Current, $V_O > V_{CC}$ Output at HIGH State | 64mA |
| | Output at LOW State | 128mA |
| I_{CC} | DC Supply Current per Supply Pin | ±64mA |
| I_{GND} | DC Ground Current per Ground Pin | ±128mA |
| T_{STG} | Storage Temperature | -65°C to +150°C |

Note:

- I_O Absolute Maximum Rating must be observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol | Parameter | Min | Max | Units |
|-----------------------|---|-----|-----|-------|
| V_{CC} | Supply Voltage | 2.7 | 3.6 | V |
| V_I | Input Voltage | 0 | 5.5 | V |
| I_{OH} | HIGH-Level Output Current | | -32 | mA |
| I_{OL} | LOW-Level Output Current | | 64 | mA |
| T_A | Free-Air Operating Temperature | -40 | 85 | °C |
| $\Delta t / \Delta V$ | Input Edge Rate, $V_{IN} = 0.8V-2.0V$, $V_{CC} = 3.0V$ | 0 | 10 | ns/V |

DC Electrical Characteristics

| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = -40°C to +85°C | | | Units | |
|----------------------|--|---------------------|--|--|---------------------|------|-------|----|
| | | | | Min. | Typ. ⁽²⁾ | Max. | | |
| V _{IK} | Input Clamp Diode Voltage | 2.7 | I _I = -18mA | | | -1.2 | V | |
| V _{IH} | Input HIGH Voltage | 2.7-3.6 | V _O ≤ 0.1V or | 2.0 | | | V | |
| V _{IL} | Input LOW Voltage | 2.7-3.6 | V _O ≥ V _{CC} - 0.1V | | | 0.8 | V | |
| V _{OH} | Output HIGH Voltage | 2.7-3.6 | I _{OH} = -100μA | V _{CC} - 0.2 | | | V | |
| | | 2.7 | I _{OH} = -8mA | 2.4 | | | | |
| | | 3.0 | I _{OH} = -32mA | 2.0 | | | | |
| V _{OL} | Output LOW Voltage | 2.7 | I _{OL} = 100μA | | | 0.2 | V | |
| | | | I _{OL} = 24mA | | | 0.5 | | |
| | | 3.0 | I _{OL} = 16mA | | | 0.4 | | |
| | | | I _{OL} = 32mA | | | 0.5 | | |
| | | | I _{OL} = 64mA | | | 0.55 | | |
| I _{I(HOLD)} | Bushold Input Minimum Drive | 3.0 | V _I = 0.8V | 75 | | | μA | |
| | | | V _I = 2.0V | -75 | | | | |
| I _{I(OD)} | Bushold Input Over-Drive Current to Change State | 3.0 | ⁽³⁾ | 500 | | | μA | |
| | | | ⁽⁴⁾ | -500 | | | | |
| I _I | Input Current | 3.6 | V _I = 5.5V | | | 10 | μA | |
| | | Control Pins | 3.6 | V _I = 0V or V _{CC} | | | | ±1 |
| | | Data Pins | 3.6 | V _I = 0V | | | | -5 |
| | | | | V _I = V _{CC} | | | | 1 |
| I _{OFF} | Power Off Leakage Current | 0 | 0V ≤ V _I or V _O ≤ 5.5V | | | ±100 | μA | |
| I _{PU/PD} | Power up/down 3-STATE Output Current | 0-1.5 | V _O = 0.5V to 3.0V, V _I = GND or V _{CC} | | | ±100 | μA | |
| I _{OZL} | 3-STATE Output Leakage Current | 3.6 | V _O = 0.5V | | | -5 | μA | |
| I _{OZH} | 3-STATE Output Leakage Current | 3.6 | V _O = 3.0V | | | 5 | μA | |
| I _{OZH+} | 3-STATE Output Leakage Current | 3.6 | V _{CC} < V _O ≤ 5.5V | | | 10 | μA | |
| I _{CCH} | Power Supply Current | 3.6 | Outputs HIGH | | | 0.19 | mA | |
| I _{CCL} | Power Supply Current | 3.6 | Outputs LOW | | | 5 | mA | |
| I _{CCZ} | Power Supply Current | 3.6 | Outputs Disabled | | | 0.19 | mA | |
| I _{CCZ+} | Power Supply Current | 3.6 | V _{CC} ≤ V _O ≤ 5.5V, Outputs Disabled | | | 0.19 | mA | |
| ΔI _{CC} | Increase in Power Supply Current ⁽⁵⁾ | 3.6 | One Input at V _{CC} - 0.6V, Other Inputs at V _{CC} or GND | | | 0.2 | mA | |

Notes:

- All typical values are at V_{CC} = 3.3V, T_A = 25°C.
- An external driver must source at least the specified current to switch from LOW-to-HIGH.
- An external driver must sink at least the specified current to switch from HIGH-to-LOW.
- This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics(6)

| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = 25°C | | | Units |
|------------------|--|---------------------|---|-----------------------|------|------|-------|
| | | | C _L = 50 pF, R _L = 500Ω | Min. | Typ. | Max. | |
| V _{OLP} | Quiet Output Maximum Dynamic V _{OL} | 3.3 | (7) | | 0.8 | | V |
| V _{OLV} | Quiet Output Minimum Dynamic V _{OL} | 3.3 | (7) | | -0.8 | | V |

Notes:

6. Characterized in SOIC package. Guaranteed parameter, but not tested.
 7. Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

| Symbol | Parameter | T _A = -40°C to +85°C, C _L = 50pF, R _L = 500Ω | | | | | Units |
|---------------------------------------|--------------------------------------|--|---------------------|------|------------------------|------|-------|
| | | V _{CC} = 3.3V ± 0.3V | | | V _{CC} = 2.7V | | |
| | | Min. | Typ. ⁽⁸⁾ | Max. | Min. | Max. | |
| t _{PLH} | Propagation Delay, Data to Output | 1.0 | | 3.5 | 1.0 | 4.5 | ns |
| t _{PHL} | | 1.0 | | 3.9 | 1.0 | 4.9 | |
| t _{PZH} | Output Enable Time | 1.0 | | 4.0 | 1.0 | 5.5 | ns |
| t _{PZL} | | 1.1 | | 4.0 | 1.1 | 5.4 | |
| t _{PHZ} | Output Disable Time | 1.5 | | 4.5 | 1.5 | 5.7 | ns |
| t _{PLZ} | | 1.3 | | 4.5 | 1.3 | 4.0 | |
| t _{OSSL} , t _{OSHL} | Output to Output Skew ⁽⁹⁾ | | | 1.0 | | 1.0 | ns |

Notes:

8. All typical values are at V_{CC} = 3.3V, T_A = 25°C.
 9. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSSL}) or LOW-to-HIGH (t_{OSHL}).

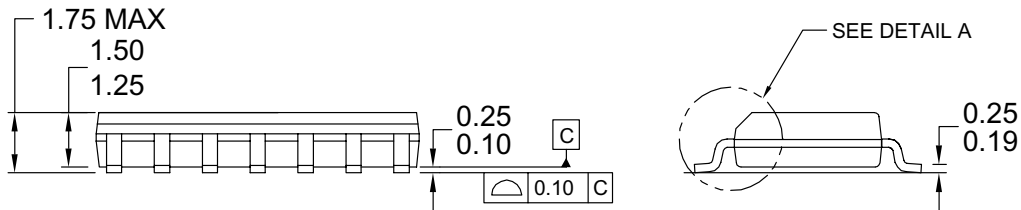
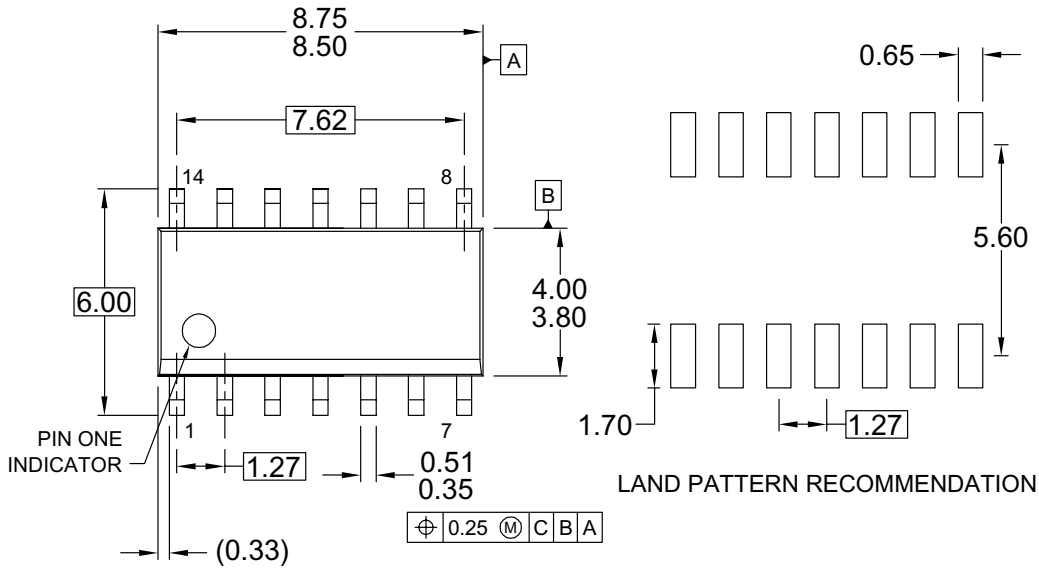
Capacitance⁽¹⁰⁾

| Symbol | Parameter | Conditions | Typical | Units |
|------------------|--------------------|--|---------|-------|
| C _{IN} | Input Capacitance | V _{CC} = 0V, V _I = 0V or V _{CC} | 4 | pF |
| C _{OUT} | Output Capacitance | V _{CC} = 3.0V, V _O = 0V or V _{CC} | 8 | pF |

Note:

10. Capacitance is measured at frequency f = 1MHz, per MIL-STD-883B, Method 3012.

Physical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

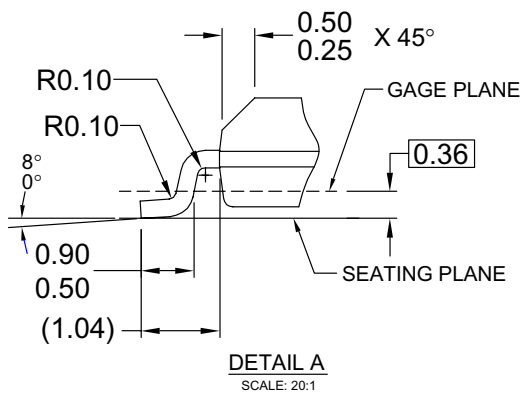


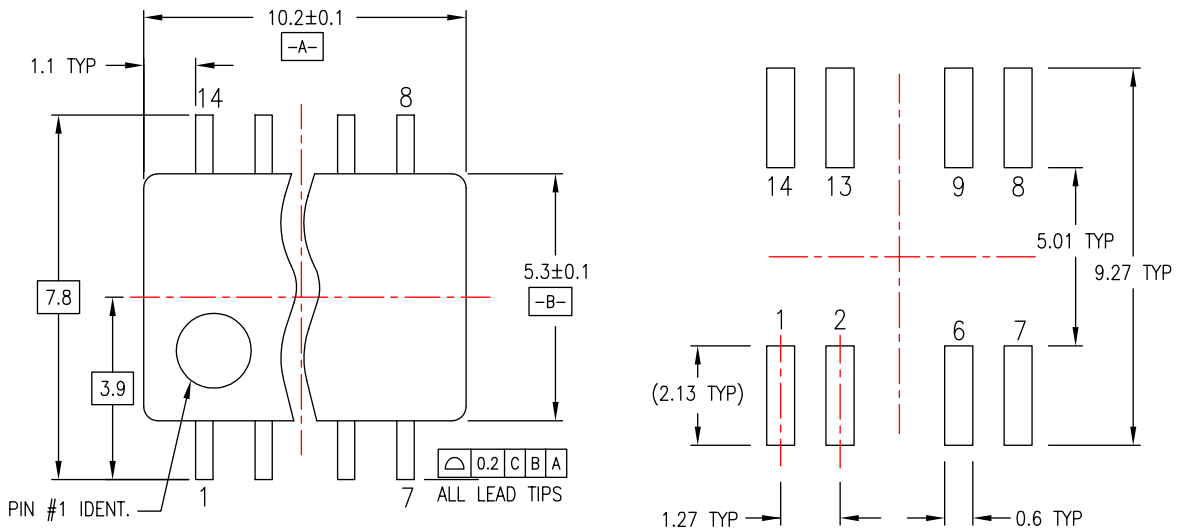
Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

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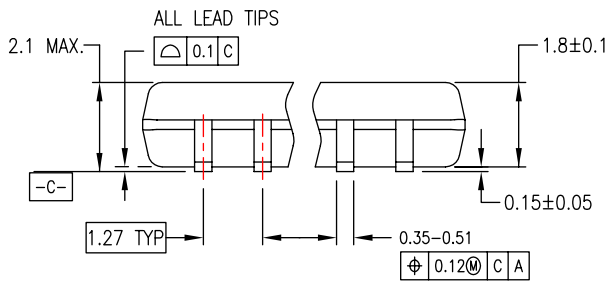
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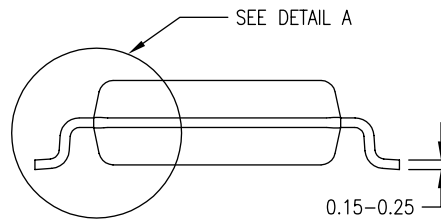
Physical Dimensions (Continued)



LAND PATTERN RECOMMENDATION

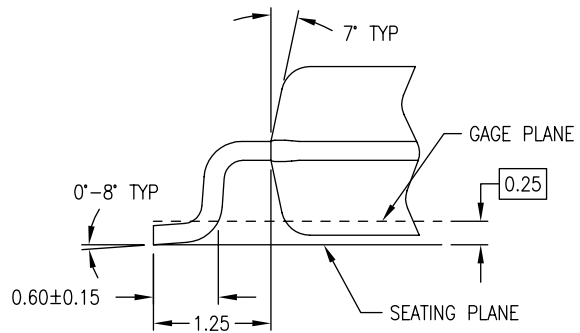


DIMENSIONS ARE IN MILLIMETERS



NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



DETAIL A

M14DREVC

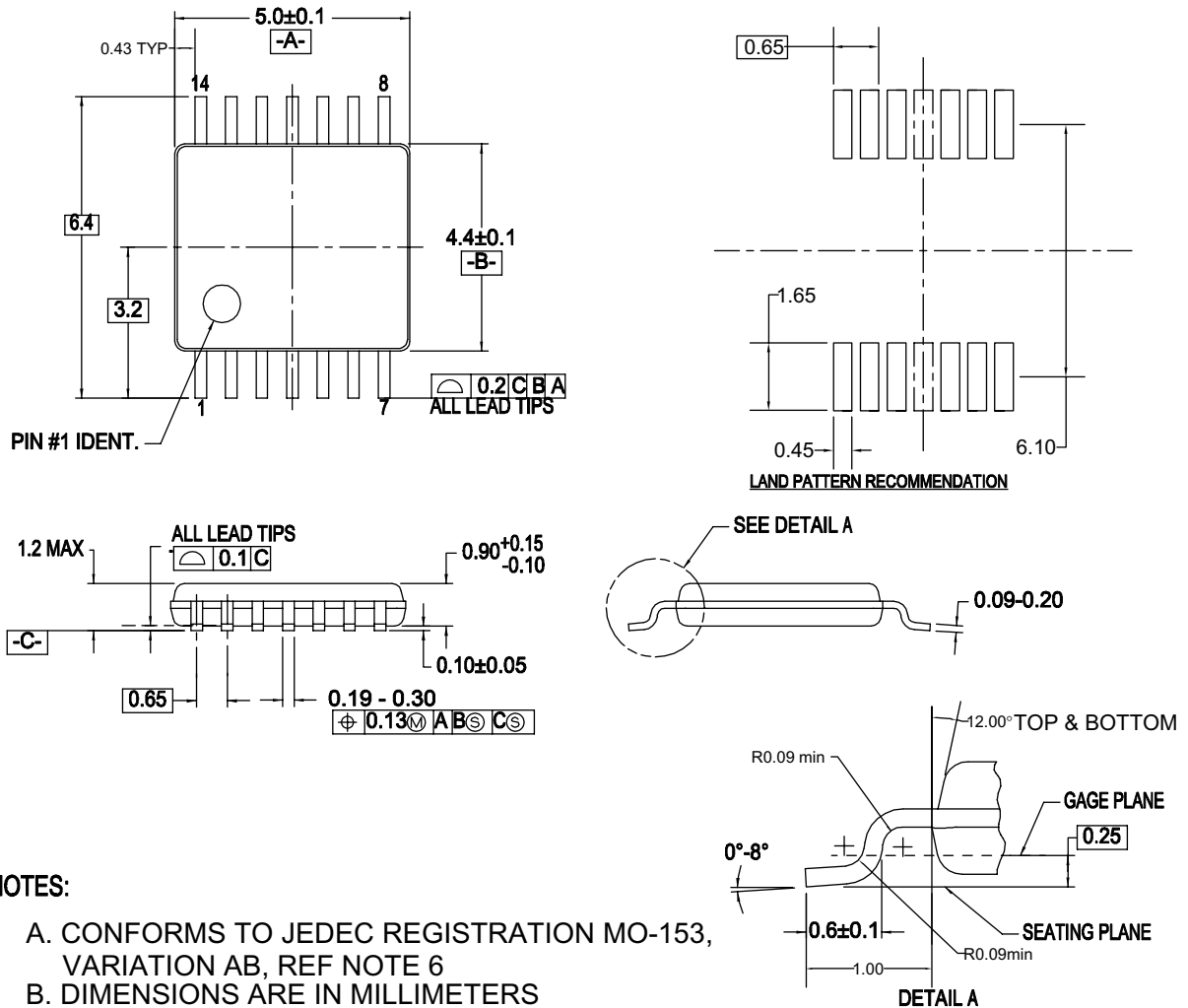
Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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Physical Dimensions (Continued)



NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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

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